

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

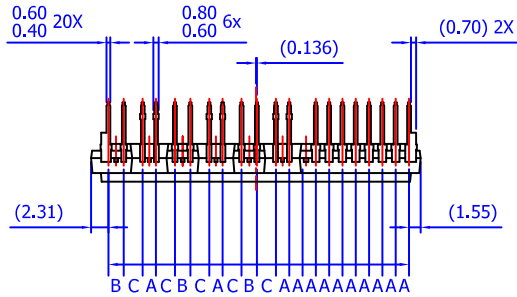
ON Semiconductor®



SPMJB-027 / 27LD, PDD STD, SPM27-JB FULL PACK SHORT LEAD

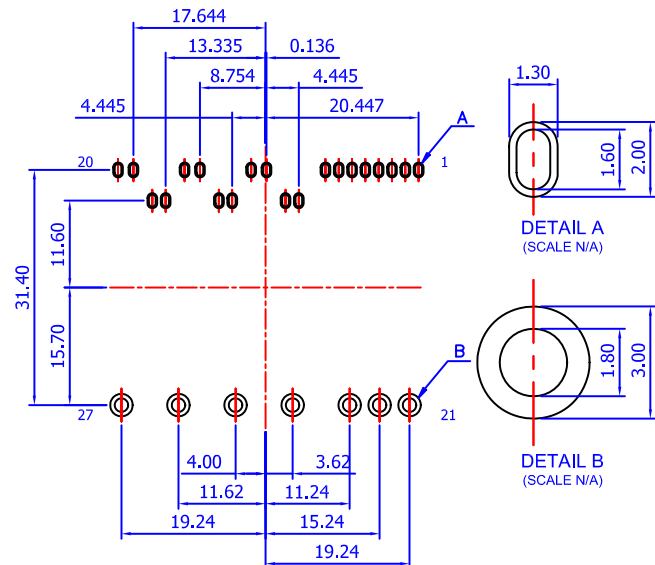
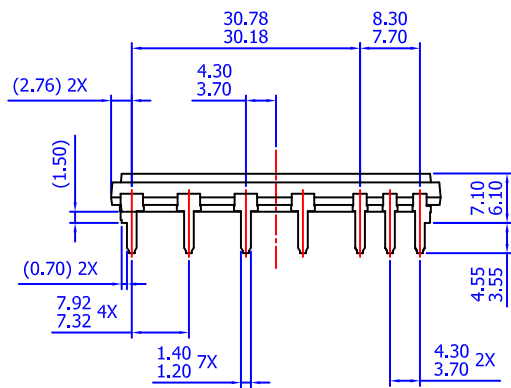
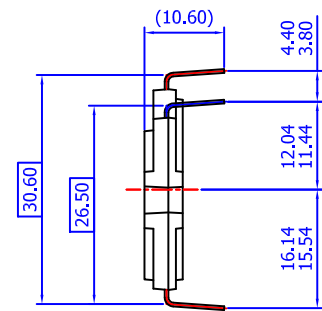
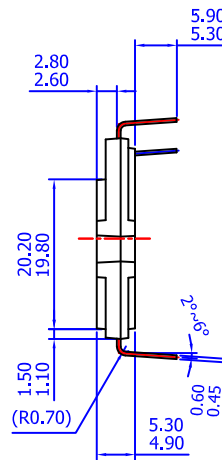
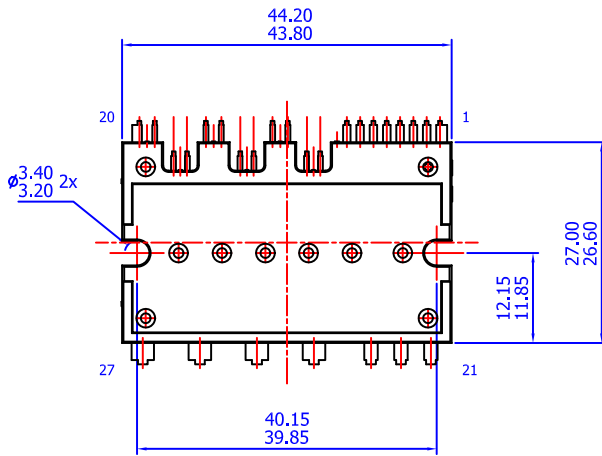
CASE MODDR
ISSUE O

DATE 31 DEC 2016



LEAD PITCH (TOLERANCE : ±0.30)

- A : 1.778
- B : 2.050
- C : 2.531



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE
 - E) [] IS ASS'Y QUALITY

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DESCRIPTION:	SPMJB-027 / 27LD, PDD STD, SPM27-JB FULL PACK SHORT LEAD	PAGE 1 OF 1

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